

09/018,783

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	695	438/687	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:34
2	BRS	L2	22142	microstructures	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:34
3	BRS	L3	✓2	- 2002/0027363 recessed adj microstructures - 2002/0000271	X USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:35
4	BRS	L4	102555	workpiece	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:35
5	BRS	L5	340	semiconductor adj workpiece	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:35
6	BRS	L6	7321	copper adj metal	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:35
7	BRS	L7	3440	electrochemical adj process	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:36
8	BRS	L8	213	copper adj grains	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:36

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L9	53791	grain adj size	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:36
10	BRS	L10	6	-2002,600430 electroplating adj waveform X	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:36
11	BRS	L11	0	copper adj grain adj size adj generation	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:36
12	BRS	L12	1761	electroplating adj solution	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:37
13	BRS	L13	3	small adj metal adj grain adj size -6,171,460 X	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:37
14	BRS	L14	71	low-K adj dielectric adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:37
15	BRS	L15	46286	dielectric adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:38
16	BRS	L16	673	copper adj metallization	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:38

	Type	L #	Hits	Search Text	DBs	Time Stamp
17	BRS	L17	9476	copper adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:38
18	BRS	L18	78307	annealing	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:38
19	BRS	L19	237	metal adj seed adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:38
20	BRS	L20	33463	barrier adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:38
21	BRS	L21	2968	seed adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:38
22	BRS	L22	7623	physical adj vapor adj deposition	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:39
23	BRS	L23	6835	adhesion adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:39
24	BRS	L24	1258	chemical adj mechanical adj polish	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:39

	Type	L #	Hits	Search Text	DBs	Time Stamp
25	BRS	L25	3826	electrolytic adj process	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:39
26	BRS	L26	50	electrolytic adj copper adj deposition	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:39
27	BRS	L27	50179	chemical adj vapor adj deposition	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:40
28	BRS	L28	153	conductive adj seed adj layer	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:46
29	BRS	L29	40	1 and 2	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:46
30	BRS	L30	1108	2 and 4	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:47
31	BRS	L31	286	2 and 4 and 9	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:49
32	BRS	L32	5	~ 2002/000/034 2 and 4 and 9 and 7 X	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:49

	Type	L #	Hits	Search Text	DBs	Time Stamp
33	BRS	L33	82	2 and 4 and 9 and 18	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:50
34	BRS	L34	138	2 and 7	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:49
35	BRS	L35	3	2 and 7 and 5	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:50
36	BRS	L36	✓32	6 and 8	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:50
37	BRS	L37	84	8 and 9	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:52
38	BRS	L38	82	2 and 4 and 9 and 18 and 9	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:51
39	BRS	L39	✓3	2 and 4 and 9 and 18 and 8 *5,707,466	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:51
40	BRS	L40	✓18	8 and 9 and 2	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:52

	Type	L #	Hits	Search Text	DBs	Time Stamp
41	BRS	L41 ✓	47	7 and 12	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:52
42	BRS	L42	255	16 and 17	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:52
43	BRS	L43 ✓	5	US2001/0042689 * 6,290,833 16 and 17 and 28 * 6,277,263 * 6,197,181	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:53
44	BRS	L44	484	15 and 20 and 21	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:53
45	BRS	L45	107	15 and 20 and 21 and 23	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:53
46	BRS	L46 ✓	6	-2001/0054769 * 6,193,155 15 and 20 and 21 and 23 and 28 * 6,132,586 * 6,121,152	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:54
47	BRS	L47 ✓	24	15 and 20 and 21 and 23 and 16	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:54
48	BRS	L48 ✓	2	-2001/0029099 -6,261,954 18 and 24 and 25	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:54

	Type	L #	Hits	Search Text	DBs	Time Stamp
49	BRS	L49	5149	22 and 27	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:55
50	BRS	L50 ✓2		22 and 27 and 24 and 25 L48	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:55
51	BRS	L51	1097	22 and 27 and 18	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:56
52	BRS	L52 ✓2		22 and 27 and 18 and 25 L48	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:56
53	BRS	L53 ✓46		22 and 27 and 18 and 24	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:56
54	BRS	L54	0	14 and 26	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:56
55	BRS	L55 ✓9		2 and 14 - 6,124,198	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:56
56	BRS	L56	0	2 and 26	USPAT; US-PGP UB; EPO; JPO	2002/03/25 18:57

	Type	L #	Hits	Search Text	DBs	Time Stamp
57	BRS	L57	11	-5,252,196 -5,004,525 12 and 26	USPAT; US-PPG UB; EPO; JPO	2002/03/25 18:57

L14
-6,324,448
-6,287,955
-6,159,842
*6,100,587

L26
X

L29
-6,355,106
*6,331,984
*6,309,969
-6,295,555
*6,218,302
*6,171,661

L36

L40
*6,297,154
-5,707,466

L41
*5,595,637
L 4,203,808

L47
-6,342,848
*6,245,672
*6,143,155
-6,132,586
6,121,152
*6,037,257

L53
-6,316,356
-6,066,577

	Comments	Error Definition	Errors
57			0

L37?

L38?

457

~~-6,344,129~~
~~-6,165,555~~
~~-6,139,701~~

~~-6,770,833~~
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